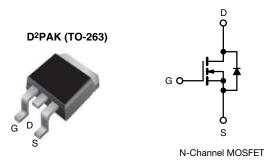




# **E Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.156		
Q <sub>g</sub> max. (nC)	96			
Q <sub>gs</sub> (nC)	12			
Q <sub>gd</sub> (nC)	25			
Configuration	Single			



#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	D <sup>2</sup> PAK (TO-263)
Lead (Pb)-Free and Halogen-Free	SiHB22N60AE-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_c = 25 \degree C$ , unless otherwise noted)								
PARAMETER			SYMBOL	LIMIT	UNIT			
Drain-Source Voltage		V <sub>DS</sub>	600	V				
Gate-Source Voltage			V <sub>GS</sub>	± 30	V			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	Γ <sub>C</sub> = 25 °C <sub>C</sub> = 100 °C	- I <sub>D</sub> -	20				
	V <sub>GS</sub> at 10 V	<sub>C</sub> = 100 °C		12	А			
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	49				
Linear Derating Factor				1.4	W/°C			
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	204	mJ			
Maximum Power Dissipation			PD	179	W			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C				
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C		al) (/alt	70	1//			
Reverse Diode dV/dt <sup>d</sup>		dV/dt	31	V/ns				
Soldering Recommendations (Peak temperature) <sup>c</sup>	For 10 s			300	°C			

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b.  $V_{DD}$  = 140 V, starting T<sub>J</sub> = 25 °C, L = 28.2 mH, R<sub>q</sub> = 25  $\Omega$ , I<sub>AS</sub> = 3.8 A.

c. 1.6 mm from case.

d.  $I_{SD} \leq I_D$ , dI/dt = 100 A/µs, starting  $T_J$  = 25 °C.

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# SiHB22N60AE

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PARAMETER	SYMBOL	TYP.		MAX.		UNIT			
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-		62					
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	- 0.7				°C/W			
	•	·							
<b>SPECIFICATIONS</b> ( $T_J = 25 \degree C$ ,	unless otherw	ise noted)							
PARAMETER	SYMBOL	-		ONS	MIN.	TYP.	MAX.	UNI	
Static									
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 25	50 µA	600	-	-	V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>C</sub>	<sub>0</sub> = 250 μA	-	0.72	-	V/°0	
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 2	50 µA	2	-	4	V	
			$V_{GS} = \pm 20 V$ $V_{GS} = \pm 30 V$		-	-	± 100	nA	
Gate-Source Leakage	I <sub>GSS</sub>				-	-	± 1	μA	
Zene Oete Malterre Duite Original		V <sub>DS</sub> =	= 600 V, V <sub>GS</sub>	s = 0 V	-	-	1		
Zero Gate Voltage Drain Current	D Gate Voltage Drain Current $I_{DSS}$ $V_{DS} = 480 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$		, T <sub>J</sub> = 125 °C	-	-	10	μA		
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 V$	I <sub>D</sub>	= 11 A	-	0.156	0.180	Ω	
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> =	11 A	-	4.8	-	S	
Dynamic						•			
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz $V_{DS} = 0 V \text{ to } 480 V, V_{GS} = 0 V$		-	1451	-	pF		
Output Capacitance	C <sub>oss</sub>			-	73	-			
Reverse Transfer Capacitance	C <sub>rss</sub>			-	5	-			
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>			-	50	-			
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	258	-			
Total Gate Charge	Qg				-	48	96	nC	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	V <sub>GS</sub> = 10 V I <sub>D</sub> = 11 A, V <sub>DS</sub> = 480 V		-	12	-		
Gate-Drain Charge	Q <sub>gd</sub>				-	25	-		
Turn-On Delay Time	t <sub>d(on)</sub>	1		-	19	38			
Rise Time	t <sub>r</sub>		- 		-	33	66	1	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{DD} = 480 \text{ V}, \text{ I}_{D} = 11 \text{ A}, \\ V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	45	90	ns		
Fall Time	t <sub>f</sub>			-	21	42			
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.3	0.6	1.2	Ω		
Drain-Source Body Diode Characterist									
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	20	A		
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	49			
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V		-	-	1.2	V		
Reverse Recovery Time	t <sub>rr</sub>	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 11 \text{ A},$ dl/dt = 100 A/µs, V <sub>R</sub> = 25 V		-	319	638	ns		
Reverse Recovery Charge	Q <sub>rr</sub>			-	4.9	9.8	μΟ		
Reverse Recovery Current	I <sub>RRM</sub>			-	28	_	A		

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

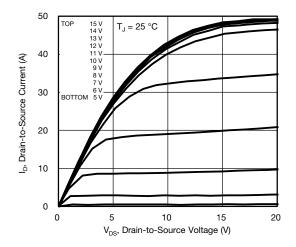


Fig. 1 - Typical Output Characteristics

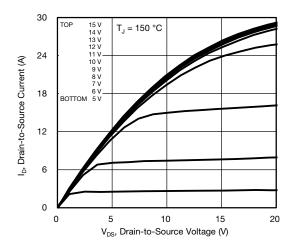
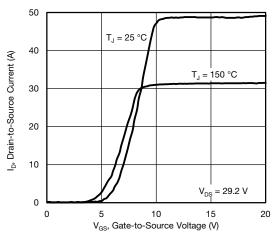


Fig. 2 - Typical Output Characteristics





S16-1715-Rev. A, 29-Aug-16

3.0 = 11 A R<sub>DS(on)</sub>, Drain-to-Source On-Resistance 2.5 2.0 (Normalized) 1.5 1.0 10 \ GS 0.5 0 -20 -60 -40 20 40 60 80 100 120 140 160 0 T<sub>J</sub>, Junction Temperature (°C)

Fig. 4 - Normalized On-Resistance vs. Temperature

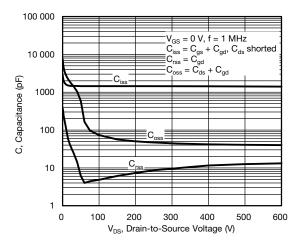


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

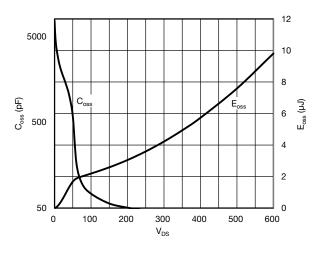


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 

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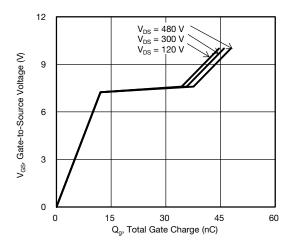


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

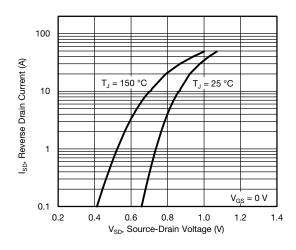


Fig. 8 - Typical Source-Drain Diode Forward Voltage

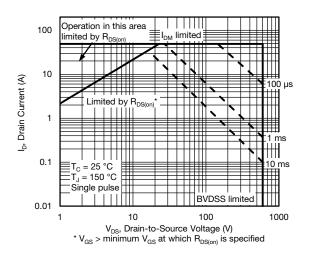


Fig. 9 - Maximum Safe Operating Area

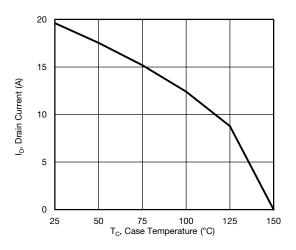


Fig. 10 - Maximum Drain Current vs. Case Temperature

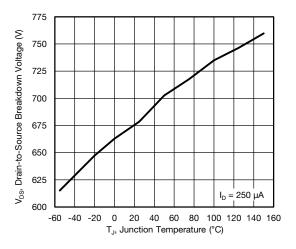


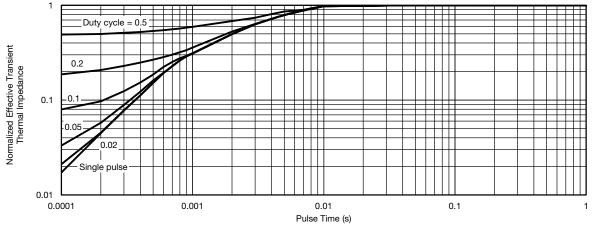
Fig. 11 - Temperature vs. Drain-to-Source Voltage

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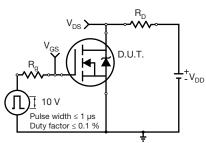


Fig. 13 - Switching Time Test Circuit

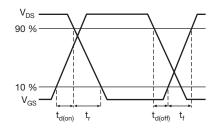


Fig. 14 - Switching Time Waveforms

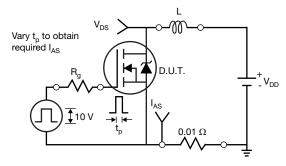


Fig. 15 - Unclamped Inductive Test Circuit

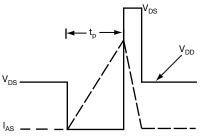


Fig. 16 - Unclamped Inductive Waveforms

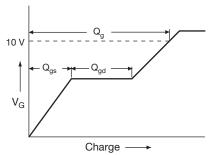


Fig. 17 - Basic Gate Charge Waveform

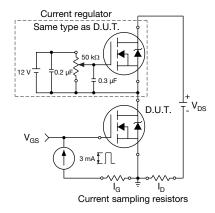


Fig. 18 - Gate Charge Test Circuit

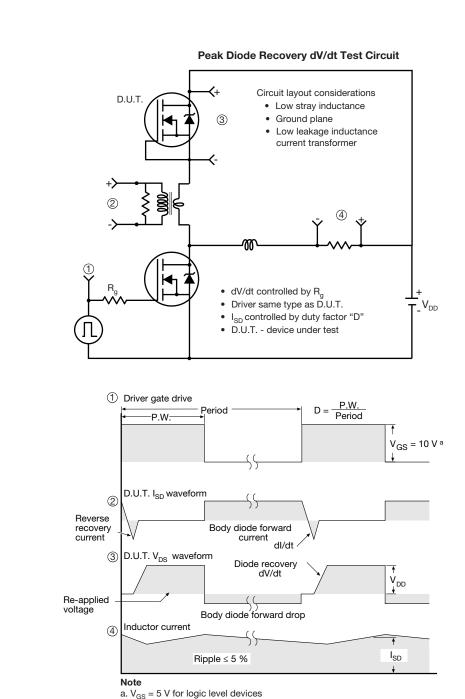


Fig. 19 - For N-Channel

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